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Solder Paste Reflow Processes

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No Clean Solder Paste Reflow

No-clean flux is really “low-residue” solder paste. Post reflow, it leaves trace amounts of noncorrosive, resinous residue on or around solder joints, varying in color from transparent to

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amber. The lower the solids content (resins, gelling agents and activators) in the paste, the lower the residue left on the board.

Why Clean, No Clean Solder Paste | No Clean Solder Flux

No clean solder pastes are popular because the flux residues do not need to

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be washed off of the circuit board after reflow. This simplifies the surface mount assembly process and improves productivity. The elimination of the wash process also allows for the use of components that cannot be exposed to water.

No Clean Solder Paste - Solder

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Paste, Solder Flux - FCT Solder

Product description No Clean (ROSIN-FREE) Flux - 60 ml. / 2 Oz. KESTER 951

Alcohol based for a very clean job. leaves only a white powder looking residue that don't require cleaning. Dries as its heated coating the solder giving the perfect flux to solder ratio for a healthy long lasting bond.

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60 ml. / 2 Oz. KESTER 951 No Clean Soldering Solder Liquid ...

EP256 is a no-clean, air or nitrogen reflowable solder paste specifically designed for maximum robustness in reflow profiling and stencil printing. EP256 has the widest possible reflow processing window. EP256 is also

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capable of stencil printing downtimes of up to 90 minutes with an effective first print down to 20 mils.

EP256 Solder Paste

No-clean solder paste is more accurately described as low-residue solder paste, says Dixon. After reflow, the flux leaves a small amount of noncorrosive,

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resinous residue on or around the solder joints. This residue varies in color from transparent to amber, depending on the reflow temperature and the flux resin.

Why Clean No-Clean? - ASSEMBLY Magazine

"No-Clean" solder paste is a misnomer. There is no such thing as a "No-Clean"

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solder paste, only a low residue solder paste, whose flux residue after reflow, may not have to be cleaned from the board, to ensure board functional reliability. No clean refers to a production process in which cleaning of the final product is deemed unnecessary.

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Problem with 'No Clean' Solder Flux Residue

Looking back twenty-five years ago, the solder pastes residues had to be cleaned after reflow due to their corrosive nature: two ways of cleaning were possible, either with solvent or by using water, with or without detergent.

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Reliability of No-clean and Water-soluble Solder Pastes

Jetting or microdispense solder pastes include no-clean and water-soluble solder pastes, and are used with SnAgCu and SnPb alloy systems. It is important that they ONLY be used with the matched printable solder pastes. These products are designed for reflow in air or

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nitrogen atmosphere of 100ppm oxygen or less.

Solder Paste | Solders | Products made by Indium Corporation

DESCRIPTION ALPHA OM-340 is a lead-free, no-clean solder paste designed for a broad range of applications. ALPHA OM-340 provides best in class low defect

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rate for Head in Pillow defects combined with excellent first pass yield on ICT/pin testing.

T E C H N I C A L B U L L E T I N **ALPHA OM-340 NO-CLEAN ...**

The majority of no-clean solder pastes are rosin or resin based, and therefore can withstand the traditional reflow

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profiles used on RMA based fluxes. The goal of the reflow process is to melt the powder particles in the solder paste, wet the surfaces being joined together, and solidify the solder to create a strong metallurgical bond.

SMT Process Recommendations Defect Minimization Methods ...

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Solder Paste ALPHA® OM-350 is a lead-free, no-clean solder paste suitable for fine feature printing and reflow using most demanding soak reflow profiles in air and nitrogen atmospheres. The outstanding reflow process window of ALPHA OM-350 delivers good soldering on OSP-Cu, Immersion Ag, Immersion Sn, ENIG and Lead-Free HASL surface

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finishes.

ALPHA®OM 350 Solder Paste | Alpha Assembly Solutions

In some cases, the residues are tolerable to the assemblies and in other cases they are not. In a recent industry pole of assemblers reflowing with no-clean paste, 53% of respondents indicated

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they clean the assemblies after reflow. Perhaps we should consider a more accurate description of no-clean flux/paste as "Low Residue".

Pros and Cons of Cleaning No-clean

NR-116+ is a no-visible-residue solder paste developed for use in nitrogen reflow applications. As a resin-free /

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rosin-free no-clean product, any remaining post-process residues may be left on the PCB without degradation.

TECHNICAL DATA SHEET - AIM Solder

LOCTITE® GC 10 is a halogen free, zero halogens added, no-clean, low voiding, Pb-free solder paste specially formulated

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to provide added long term stability over a wide range of temperature conditions. The enhanced paste stability created through its novel formulation strategy increases both field application yields and on-line paste utilization.

**LOCTITE GC 10 - Electronics -
Henkel Adhesives**

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Lead-Free No-Clean Solder Paste Our 592-series No-Clean solder paste is available in two lead-free solder alloys, SAC305 (Sn96.5/Ag3/Cu0.5) and the Sn96.5/Ag3.5. The SAC305 is currently available in Type 3, Type 4 and Type 5 mesh size; the Sn96.5/Ag3.5 is available in Type 3 mesh size. Contact us if you need additional mesh sizes.

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Lead-Free No-Clean Solder Paste - Superior Flux Home Page

Summary: Rosin-based no-clean solder pastes are the most widely used solder pastes in the world and dominate consumer electronics assembly. The most common rosin-based no-clean solder paste reflow environment is air,

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which has some obvious advantages such as no-cost and tombstoning mitigation. However, there are a number of manufacturers that use a nitrogen reflow environment for reasons ranging from “shinier” solder joints to head-in-pillow (a.k.a. head-on-pillow) defect mitigation.

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Whitepapers | Technical Documents | Indium Corporation

Solder pastes with a IPC J-STD-004 classification of ROL0 or ROL1 rely heavily on two basic mechanisms to render the flux residue as “no-clean”: (1) the encapsulating properties that the rosin provides and (2) the heat activation/decomposition of the

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chemicals in the flux, commonly known as “activators.”

The Effect of Reflow Profiling on the Electrical ...

EP256 is a no-clean, air or nitrogen reflowable solder paste specifically designed for maximum robustness in reflow profiling and stencil printing.

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EP256 has the widest possible reflow processing window. EP256 is also capable of stencil printing downtimes of up to 90 minutes with an effective first print down to 20 mils.

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